

1. NAME John Doe 1234 Main St
City, State, Zip
 2. DATE 10/10/77
 3. TIME 10:00 AM
 4. FROM John Doe
 5. TO John Doe
 6. SUBJECT John Doe
 7. REMARKS John Doe
 8. INITIALS JD
 9. SIGNATURE John Doe
 10. DATE 10/10/77
 11. TIME 10:00 AM
 12. FROM John Doe
 13. TO John Doe
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 BKS Ltd.
 DAG

⚡ [HLS](#) ⌚ [Details](#)

- ☐ Drafts
 - ☐ BFS: warp and 1 and 2
 - ☐ BFS: 5 and
 - ☐ BFS:
- ☐ Pending
- ☒ Active
 - ☒ L1: 198566: (diamond (uni nickel) adj5 diamond) garnet (silicon adj) carbide: sic)
 - ☒ L2: 117798: 1 with particle
 - ☒ L3: 23541: 1 with (hard and particle)
 - ☒ L4: (E) 3 and (flip with chip)
 - ☒ L5: (C6) 3 and (semiconductor chip die is (integrated adj) circuit)
 - ☒ L6: 2541: (pl board) pcb ch (printed adj3 board) substrate: and *
 - ☒ L7: (C6) plated adj5 (plated adj4 uni nickel)
 - ☒ L8: (C) 6 and 7
 - ☒ L9: 117121: (plated adj1 uni nickel)
 - ☒ L10: 110: 5 and 6
- ☐ Failed
 - ☐ (C) (assy electromagnetic radiation if (loaded adj5 (silicone rubber urethanes carbon plastic) f.c.))
 - ☐ (C) 4 same *
 - ☐ (C) 15 with 1
 - ☐ (C) (dummy with (semiconductor chip die is (integrated adj) circuit) and 10)
- ☐ Saved
- ☐ Favorites
- ☐ Tagged
- ☐ HHC
- ☐ Queue
- ☐ Trash

DB:	USPAT, US PGRUB, EPO, JP, Publi	Synonym
Default operator:	OR	Highlight all hit terms only
<input type="text" value="2 and 9"/>		
<input type="button" value="BFS Item"/> <input type="button" value="Edit Item"/> <input type="button" value="Image"/> <input type="button" value="Text"/>		

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval C	Inventor	S	C	P	3
1	<input type="checkbox"/>	<input type="checkbox"/>	US 5301033:345 A1		15	Exhausted radiation sensor, power semiconductor				Araki, Kiyoshi , Kida, Masahiro	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6109074 B1	20010206	27	Substrate material for mounting a semiconductor	429/472	429/323 : 428/305		Yamagata, Shinichi , et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6117433 A	20000912	18	Micro texture media made by polishing of a selectively	427/537	427/128 : 427/150		Xong, Xavier , et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6054193 A	20000425	19	Method for making CVD diamond coated substrate for	427/249.0	427/122 : 427/249.11		Zimmer, Jerry W. , et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5	<input type="checkbox"/>	<input type="checkbox"/>	US 5930722 A	19991109	19	Plated aluminum alloy, cylinder block thereof,	305/219	305/640		Kuroda, Tetsuya , et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6	<input type="checkbox"/>	<input type="checkbox"/>	US 5921856 A	19990713	14	CVD diamond coated substrate for polishing pad	451/539	451/926		Zimmer, Jerry W.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
7	<input type="checkbox"/>	<input type="checkbox"/>	US 5759607 A	19980602	9	Diamond wire drawing die and process for manufacturing	429/132	429/131 : 428/212		Takahashi, Toshiya , et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8	<input type="checkbox"/>	<input type="checkbox"/>	US 5521236 A	19961105	9	Diamond wire drawing die	72/467			Takahashi, Toshiya , et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9	<input type="checkbox"/>	<input type="checkbox"/>	US 5273782 A	19931228	44	Coated parts with film having powder skeleton	427/242	205/03 : 427/11		Sagawa, Masato , et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10	<input type="checkbox"/>	<input type="checkbox"/>	US 5269839 A	19931214	9	Electroless plating solution and plating method with it	106/1,22	106/1,27 : 427/438		Inoue, Manabu , et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

Servers Queue Date

DB: USPAT, US PGRUE, EPO, ☒ Enrich ☒ Synchronise

Default operator : DR ☒ Highlight all hit terms only

16 rows 10

☒ ORS term ☒ IAR term ☒ Image ☒ Text

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BRS: warp and 1 and 2
BRS: " and
BRS:
BRS: 11 and

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Active

- U2: (17776): 1 with particle
- U3: (1354): 1 with (hard and particle)
- U4: (6): 5 and (chip with chip)
- U5: (66): 3 and (semiconductor chip die in (integrated adj circuit))
- U6: (149): (pb board pcb cb (printed adj3 board) substrate) and 1
- U7: (564): plated adj5 (plated adj4 (ni nickel))
- U8: (0): 6 and 7
- U9: (11712): (plated adj5 (ni nickel))
- U10: (114): 3 and 4
- U11: (83): (pb board pcb cb (printed adj3 board)) and 5
- U12: (0): 11 and 4
- U13: (0): 438,57.cols.
- U14: (114610): 498/57.cols.
- U15: (127537): 257/57.cols.
- U16: (226813): 14,15
- U17: (0): 16 and 11

(c) 100% electromagnetic radiation at loaded adsorbent (silicone rubber urethanes carbon plastic foams)
 (d) 4 same as
 (e) 10' with 1
 (f) Same as with Swenson factor, thin dielectric, untreated adsorbent and 10'

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval C	Inventor	S	C	P	3
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6166432 A	20001026	11	Substrate for use in wafer attracting apparatus and	257/731	277/102		Ohno, Masashi ; et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2	<input type="checkbox"/>	<input type="checkbox"/>	US 1934395 A	19961110	5	Non-metallurgical connection between an integrated	439/107	439/105		Euschnkow, Milton L.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3	<input type="checkbox"/>	<input type="checkbox"/>	US 4979019 A	19901218	26	Printed circuit board with inorganic insulating matrix	257/747	174/258 ; 174/251R		Pequet, Edward L. ; et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>